

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Kenji KAMIMURA et al. : Attn: BOX PCT
Serial No. NEW : Docket No. 2001-0076A
Filed March 14, 2001 :

POLISHING APPARATUS
[Corresponding to PCT/JP01/00382
Filed January 22, 2001]

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

Prior to examination of the above-referenced U.S. patent application please amend the application as follows:

IN THE CLAIMS

Please amend the claims as follows:

1. (Amended) A polishing apparatus with a polishing table having a polishing surface and a top ring for pressing a workpiece to be polished at a predetermined pressure with interposing said workpiece between said polishing table and said top ring to polish said workpiece, said polishing apparatus comprising:

at least two dressing units for dressing said polishing surface by being brought into contact with said polishing surface.

3. (Amended) A polishing apparatus according to claim 1, wherein:

at least one dressing unit is a dressing unit comprising a dresser having a size larger than a diameter of said workpiece to be polished; and

at least one dressing unit is a dressing unit comprising a dresser having a size smaller than said diameter of said workpiece to be polished.

4. (Amended) A dressing method for dressing a polishing surface provided in a polishing apparatus, wherein:

initially conditioning said polishing surface before use in the polishing, by a dressing unit comprising a diamond dresser or an SiC dresser; and

conditioning said polishing surface between processes of polishing said workpiece to be polished, by a dressing unit comprising a brush dresser.

5. (Amended) A dressing method for dressing a polishing surface provided in a polishing apparatus, wherein:

initially conditioning said polishing surface before use in the polishing, by a dressing unit comprising a diamond dresser or an SiC dresser; and

between processes of polishing said workpiece to be polished, firstly conditioning said polishing surface by a dressing unit comprising a diamond dresser or an SiC dresser, and then conditioning said polishing surface by a dressing unit comprising a brush dresser.

6. (Amended) A dressing method for dressing during polishing of a workpiece to be polished in a polishing apparatus, wherein:

dressing is performed while moving a dressing unit comprising a dresser having a size smaller than a diameter of said workpiece to be polished; and

after polishing operation is finished, dressing is performed by a dressing unit comprising a dresser having a diameter larger than said workpiece to be polished.

Please add the following new claims:

--17 A polishing apparatus for polishing a workpiece, comprising
a table for providing a polishing surface;
a first dresser having a contact surface for contacting said polishing surface during
dressing operation;
a second dresser having a contact surface for contacting said polishing surface during
dressing operation; and
an atomizer for spraying a fluid on said polishing surface to remove a polishing waste on
said polishing surface.

18. A polishing apparatus for polishing a workpiece, comprising:
a table for providing a polishing surface;
a first dresser having a contact surface for contacting said polishing surface during
dressing operation;
a second dresser having a contact surface for contacting said polishing surface during
dressing operation;
a sensor for measuring a profile of said polishing surface; and
a controller for controlling a dressing process of said first dresser.

19. A polishing apparatus according to claim 3, wherein dressers in said at least two
dressing units comprise a ring shaped dresser or a disk shaped dresser.--

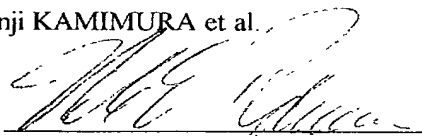
REMARKS

The above amendments have been made to make preferred changes to the claims.

Respectfully submitted,

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